

Data requirements for semiconductor die —

Part 5-2: Particular requirements and recommendations for die types — Bare die with added connection structures

ICS 31.080.01

National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/547, Known good-die, which has the responsibility to:

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Cross-references

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Summary of pages

This document comprises a front cover, an inside front cover, the ES title page, pages 2 to 9, and a back cover.

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Amendments issued since publication

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